

Quarterly Progress Report:

Project Number and Title: 1.8: Enhancing Intelligent Compaction with Passive Wireless Sensors

Research Area: Thrust # 1, Monitoring and Assessment for Enhanced Life

PI: Ehsan Ghazanfari, The University of Vermont **Co-PI(s):** Hamid Ossareh, The University of Vermont

Reporting Period: 10/1/2020 to 12/31/2020

Submission Date: *12/29/2020*

Overview:

During the past quarter, we continued to analyze the intelligent compaction (IC), pavement quality indicators, and nuclear gauge density data that we collected from field tests in Route 117 (Vermont) reclaimed asphalt pavement project as well as the data collected from another reclaimed stabilized base project in Vermont. The reliability of IC measurement values (ICMVs) and utilization of ICMVs as a function of vibration amplitude and frequency in the control system to optimize the compaction process and minimize the spatial variability of the ICMVs were investigated. The preliminary testing of the pressure sensor in underway and exploring viable options for the design/ruggedization of the sensor to survive the extreme pressure and temperature during compaction process is ongoing. The performed work in previous months helps us move closer toward the next steps of the project and to improve the IC performance and facilitate the process of geomaterial compaction and pavement performance monitoring.

Table 1: Task Progress							
Task Number Start Date End Date % Complete							
Task 1: IC in sub-	07/01/2018	08/30/2020	90%				
base/asphalt	07/01/2018	08/30/2020					
Task 2: Passive sensor	06/01/2019	09/30/2021	65%				
Task 3: Integration			15%				
options/performance	09/01/2020	12/31/2021					
eval.							
Overall Project:	07/01/2019	12/31/2021	65%				

Table 2: Budget Progress				
Project Budget	Spend – Project to Date	% Project to Date*		
\$254,732	\$170,115	64.7%		

Table 3: Presentations at Conferences, Workshops, Seminars, and Other Events					
Title	Event	Type	Location	Date(s)	
Presentation title	Name of event (i.e. TIDC 1 st Annual Conference)	i.e. Conference, Symposium, Seminar,			
Improving performance of intelligent compaction	TIDC Annual Student Poster Contest	Symposium	Virtual	9/25/2020	

Table 4: Publications and Submitted Papers and Reports						
Type	Type Title Citation Date Status					
The revised version of the submitted conference paper (4th International Conference on Transportation						
Geotechnics), reported in previous quarterly report, is under review.						

Participants and Collaborators:

Rev: 02.03.2020



Table 5: Active Principal Investigators, faculty, administrators, and Management Team Members				
Individual Name	Email Address	Department	Role in Research	
		Civil &	Principal Investigator	
Ehsan Ghazanfari	Ehsan.ghazanfari@uvm.edu	Environmental		
		Engineering		
		Electrical and	Co-Principal Investigator	
Hamid Ossareh	Hamid.Ossareh@uvm.edu	Biomedical		
		Engineering		

Table 6: Student Participants during the reporting period						
Student Name Email Address Class Major Role in research						
Maziar Foroutan		Ph.D.	Civil & Environmental Engineering	Graduate Research Assistant		
Ahmad Ghazanfari		M.S.	Electrical and Biomedical Engineering	Graduate Research Assistant		

Table 7: Student Graduates					
Student Name Role in Research Degree Graduation Date					
None					

Table 8: Research Project Collaborators during the reporting period						
	Contribution to the Project					
Organization	Location	ation Financial In-Kind Facilities Collabora				Personnel
		Support	Support	racilities	Research	Exchanges
None					_	

Table 9: Other Collaborators					
Collaborator Name and Title Contact Information Contact Information Contact Information Organization and Department Research					

Name: Callie Ewald

Title: Geotechnical Engineering Manager

Organization: Vermont Agency of Transportation

Location (City & State): Berlin, Vermont Email Address: callie.ewald@vermont.gov

Changes:

None.

Planned Activities:

(i) analysis of the collected data from IC field tests aiming at IC performance improvement

(ii) continue sensor testing and improving the design and ruggedization of the sensor in IC compaction